

RoHS

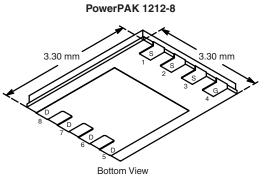
COMPLIANT HALOGEN

Available

Vishay Siliconix

N-Channel 220-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)		
220	0.320 at V _{GS} = 10 V	8.4	9.1 nC		
	0.340 at V _{GS} = 6 V	8.2	9.1110		



Bottom view

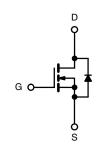
Ordering Information: Si7302DN-T1-E3 (Lead (Pb)-free) Si7302DN-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21
 Available
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested

APPLICATIONS

• Primary Side Switching



N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	220	V	
Gate-Source Voltage		V _{GS}	± 20	- v	
	T _C = 25 °C		8.4		
Continuous Drain Current ($T_1 = 150 \ ^{\circ}C$)	T _C = 70 °C	1-	6.7		
Continuous Drain Current (1j = 150°C)	T _A = 25 °C	I _D	2.3 ^{b, c}	A	
	T _A = 70 °C		1.8 ^{b, c}		
Pulsed Drain Current		I _{DM}	10		
Continuous Source-Drain Diode Current	T _C = 25 °C	L	8.4		
	T _A = 25 °C	I _S	3.2 ^{b, c}	1	
	T _C = 25 °C		52		
Maximum Power Dissipation	T _C = 70 °C	P _D	33	w	
	T _A = 25 °C	' D	3.8 ^{b, c}	vv	
	T _A = 70 °C		2.0 ^{b, c}		
Operating Junction and Storage Temperature R	Т _Ј , Т _{stg}	- 55 to 150	°C		
Soldering Recommendations (Peak Temperature) ^{d, e}		Ť	260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, f}		R _{thJA}	26	33	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.9	2.4	0/11	

Notes:

a. Based on $T_C = 25$ °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. See Solder Profile (<u>www.vishay.com/ppg?73257</u>). The PowerPAK 1212-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under Steady State conditions is 81 °C/W.

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Si7302DN

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_{D} = 250 \mu A$	220			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		240		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	5 .		7.7			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V$, $V_{GS} = 20 V_{GS}$			100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 220 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ	
		V_{DS} = 220 V, V_{GS} = 0 V, T_{J} = 55 °C			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	10			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 2.3 \text{ A}$		0.260	0.320		
		$V_{GS} = 6 \text{ V}, \text{ I}_{D} = 2.2 \text{ A}$		0.280	0.340	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 2.3 A		11		S	
Dynamic ^b							
Input Capacitance	C _{iss}			645		pF	
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		72			
Reverse Transfer Capacitance	C _{rss}			47			
Tabal Qaba Qhaana	Qg	$V_{DS} = 110 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 2.3 \text{ A}$		14	21		
Total Gate Charge		$V_{DS} = 110 \text{ V}, V_{GS} = 6 \text{ V}, I_D = 2.3 \text{ A}$		9.1	14	nC	
Gate-Source Charge	Q _{gs}			2.8			
Gate-Drain Charge	Q _{gd}			4.2			
Gate Resistance	Rg	V _{GS} = 0.1 mV, f = 1 MHz	0.9	1.8	2.7	Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	t _r	V_{DD} = 110 V, R_L = 110 Ω		10	15	- ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 1 A, V_{GEN} = 4.5 V, R_g = 6 Ω		20	30		
Fall Time	t _f			15	25		
Drain-Source Body Diode Characteristi	cs T _C = 25 °C	C, unless otherwise noted					
Continuous Source-Drain Diode Current	ا _S				8.4	^	
Pulse Diode Forward Current	I _{SM}				10	A	
Body Diode Voltage	V _{SD}	$I_{S} = 3.2 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			65	100	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 3.2 A, dl/dt = 100 A/μs, T _{.1} = 25 °C		163	250	nC	
Reverse Recovery Fall Time	t _a	$F = 0.2 \text{ A}, \text{ u/ut} = 100 \text{ A/}\mu\text{s}, T_{\text{J}} = 20 \text{ C}$		45			
Reverse Recovery Rise Time	t _b			20		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

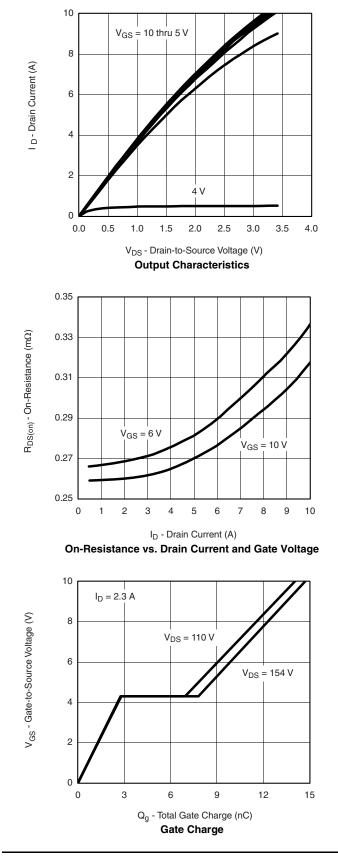
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

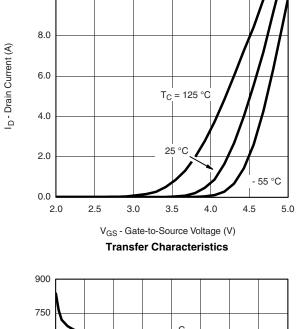


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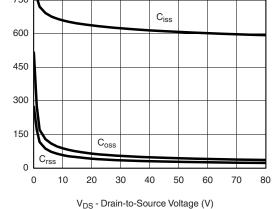
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



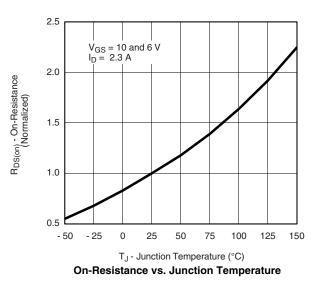


10.0

C - Capacitance (pF)



Capacitance



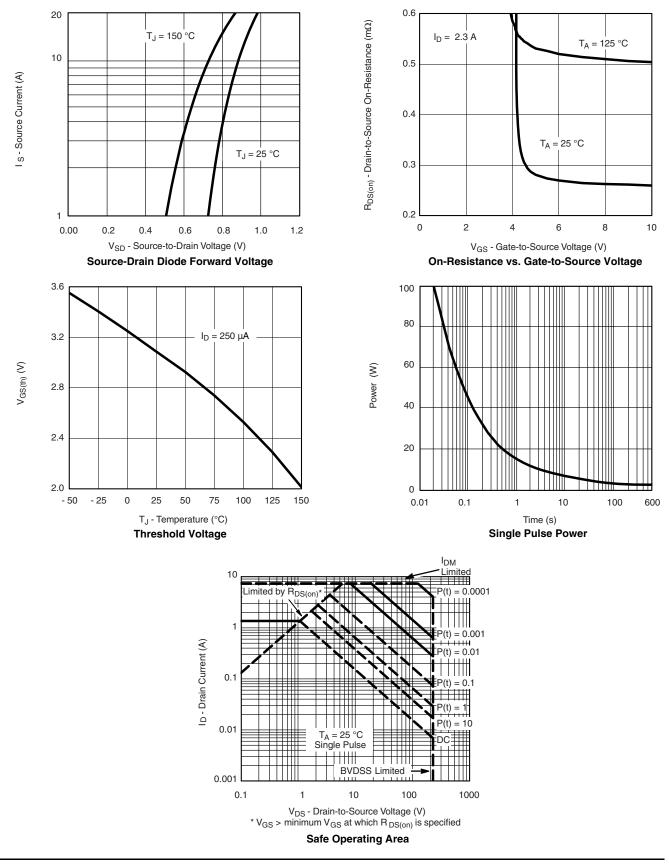
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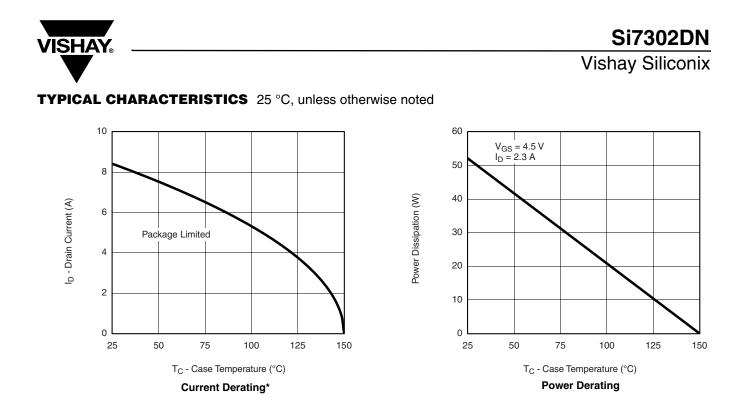


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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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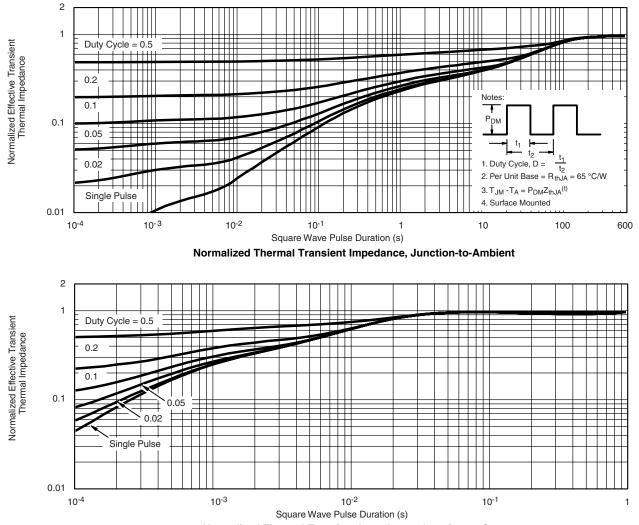


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?73306.



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